

TP3064, TP3067

Enhanced Serial Interface CMOS CODEC/Filter COMBO



Literature Number: SNAS570

TP3064, TP3067 "Enhanced" Serial Interface CMOS CODEC/Filter COMBO®

General Description

The TP3064 (μ -law) and TP3067 (A-law) are monolithic PCM CODEC/Filters utilizing the A/D and D/A conversion architecture shown in *Figure 1*, and a serial PCM interface. The devices are fabricated using National's advanced double-poly CMOS process (microCMOS).

Similar to the TP305X family, these devices feature an additional Receive Power Amplifier to provide push-pull balanced output drive capability. The receive gain can be adjusted by means of two external resistors for an output level of up to $\pm 6.6V$ across a balanced 600Ω load.

Also included is an Analog Loopback switch and a $\overline{TS}_X$ output.

See also AN-370, "Techniques for Designing with CODEC/Filter COMBO Circuits."

Features

- Complete CODEC and filtering system including:
 - Transmit high-pass and low-pass filtering
 - Receive low-pass filter with $\sin x/x$ correction
 - Active RC noise filters
 - μ -law or A-law compatible COder and DECoder
 - Internal precision voltage reference
 - Serial I/O interface
 - Internal auto-zero circuitry
 - Receive push-pull power amplifiers
- μ -law—TP3064
- A-law—TP3067
- Designed for D3/D4 and CCITT applications
- $\pm 5V$ operation
- Low operating power—typically 70 mW
- Power-down standby mode—typically 3 mW
- Automatic power-down
- TTL or CMOS compatible digital interfaces
- Maximizes line interface card circuit density

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Block Diagram

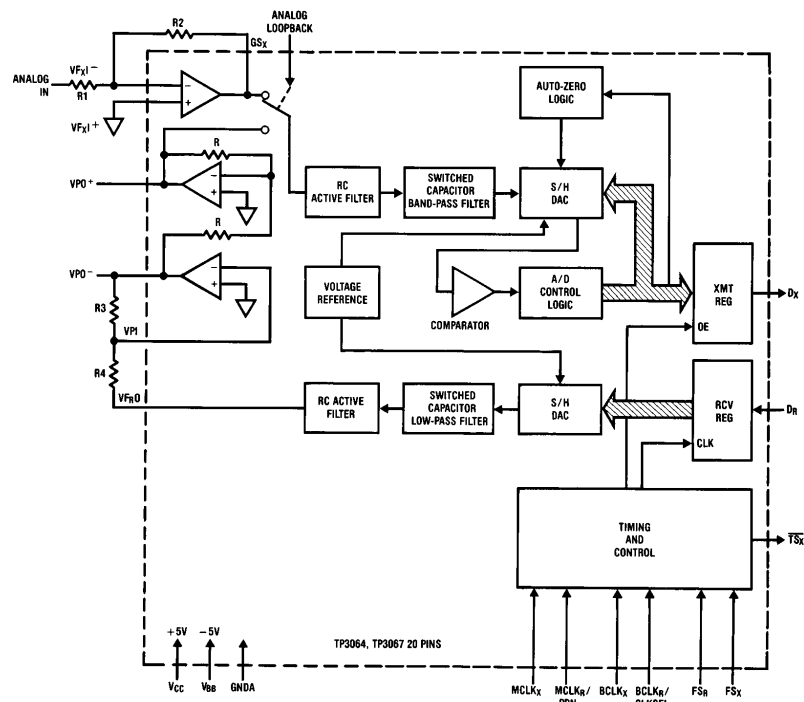
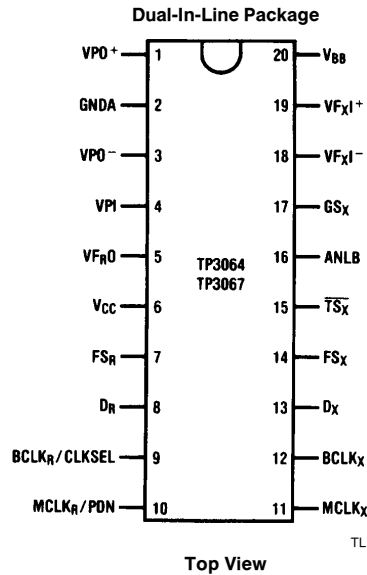


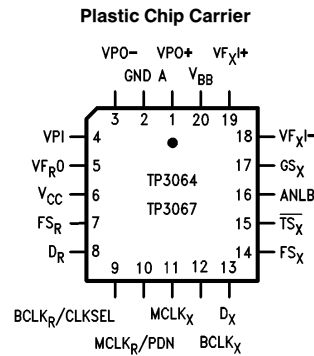
FIGURE 1

TL/H/5070-1

Connection Diagrams



TL/H/5070-2



TL/H/5070-6

Order Number TP3064J or TP3067J
See NS Package J20A

Order Number TP3064WM or TP3067WM
See NS Package M20B

Order Number TP3064N or TP3067N
See NS Package N20A

Order Number TP3064V or TP3067V
See NS Package V20A

Pin Description

Symbol	Function
VPO ⁺	The non-inverted output of the receive power amplifier.
GNDA	Analog ground. All signals are referenced to this pin.
VPO ⁻	The inverted output of the receive power amplifier.
VPI	Inverting input to the receive power amplifier.
VFR0	Analog output of the receive filter.
VCC	Positive power supply pin. VCC = +5V ± 5%.
FSR	Receive frame sync pulse which enables BCLKR to shift PCM data into DR. FSR is an 8 kHz pulse train. See <i>Figures 2 and 3</i> for timing details.
DR	Receive data input. PCM data is shifted into DR following the FSR leading edge.
BCLKR/CLKSEL	The bit clock which shifts data into DR after the FSR leading edge. May vary from 64 kHz to 2.048 MHz. Alternatively, may be a logic input which selects either 1.536 MHz/1.544 MHz or 2.048 MHz for master clock in synchronous mode and BCLKX is used for both transmit and receive directions (see Table I).
MCLKR/PDN	Receive master clock. Must be 1.536 MHz, 1.544 MHz or 2.048 MHz. May be asynchronous with MCLKX, but should be synchronous with MCLKX for best performance. When MCLKR is connected continuously low, MCLKX is selected for all internal timing. When MCLKR is connected continuously high, the device is powered down.

Symbol	Function
MCLKX	Transmit master clock. Must be 1.536 MHz, 1.544 MHz or 2.048 MHz. May be asynchronous with MCLKR. Best performance is realized from synchronous operation.
BCLKX	The bit clock which shifts out the PCM data on DX. May vary from 64 kHz to 2.048 MHz, but must be synchronous with MCLKX.
DX	The TRI-STATE [®] PCM data output which is enabled by FSX.
FSX	Transmit frame sync pulse input which enables BCLKX to shift out the PCM data on DX. FSX is an 8 kHz pulse train, see <i>Figures 2 and 3</i> for timing details.
TSX	Open drain output which pulses low during the encoder time slot.
ANLB	Analog Loopback control input. Must be set to logic '0' for normal operation. When pulled to logic '1', the transmit filter input is disconnected from the output of the transmit preamplifier and connected to the VPO ⁺ output of the receive power amplifier.
GSX	Analog output of the transmit input amplifier. Used to externally set gain.
VFxI ⁻	Inverting input of the transmit input amplifier.
VFxI ⁺	Non-inverting input of the transmit input amplifier.
VBB	Negative power supply pin. VBB = -5V ± 5%.

Functional Description

POWER-UP

When power is first applied, power-on reset circuitry initializes the COMBO™ and places it into a power-down state. All non-essential circuits are deactivated and the D_X , V_{FO} , V_{PO-} and V_{PO+} outputs are put in high impedance states. To power-up the device, a logical low level or clock must be applied to the $MCLK_R$ /PDN pin and FS_X and/or FS_R pulses must be present. Thus, 2 power-down control modes are available. The first is to pull the $MCLK_R$ /PDN pin high; the alternative is to hold both FS_X and FS_R inputs continuously low—the device will power-down approximately 2 ms after the last FS_X or FS_R pulse. Power-up will occur on the first FS_X or FS_R pulse. The TRI-STATE PCM data output, D_X , will remain in the high impedance state until the second FS_X pulse.

SYNCHRONOUS OPERATION

For synchronous operation, the same master clock and bit clock should be used for both the transmit and receive directions. In this mode, a clock must be applied to $MCLK_X$ and the $MCLK_R$ /PDN pin can be used as a power-down control. A low level on $MCLK_R$ /PDN powers up the device and a high level powers down the device. In either case, $MCLK_X$ will be selected as the master clock for both the transmit and receive circuits. A bit clock must also be applied to $BCLK_X$ and the $BCLK_R$ /CLKSEL can be used to select the proper internal divider for a master clock of 1.536 MHz, 1.544 MHz or 2.048 MHz. For 1.544 MHz operation, the device automatically compensates for the 193rd clock pulse each frame.

With a fixed level on the $BCLK_R$ /CLKSEL pin, $BCLK_X$ will be selected as the bit clock for both the transmit and receive directions. Table I indicates the frequencies of operation which can be selected, depending on the state of $BCLK_R$ /CLKSEL. In this synchronous mode, the bit clock, $BCLK_X$, may be from 64 kHz to 2.048 MHz, but must be synchronous with $MCLK_X$.

Each FS_X pulse begins the encoding cycle and the PCM data from the previous encode cycle is shifted out of the enabled D_X output on the positive edge of $BCLK_X$. After 8 bit clock periods, the TRI-STATE D_X output is returned to a high impedance state. With an FS_R pulse, PCM data is latched via the D_R input on the negative edge of $BCLK_X$ (or $BCLK_R$ if running). FS_X and FS_R must be synchronous with $MCLK_X/R$.

TABLE I. Selection of Master Clock Frequencies

BCLK _R /CLKSEL	Master Clock Frequency Selected	
	TP3067	TP3064
Clocked	2.048 MHz	1.536 MHz or 1.544 MHz
0	1.536 MHz or 1.544 MHz	2.048 MHz
1	2.048 MHz	1.536 MHz or 1.544 MHz

ASYNCHRONOUS OPERATION

For asynchronous operation, separate transmit and receive clocks may be applied. $MCLK_X$ and $MCLK_R$ must be 2.048 MHz for the TP3067, or 1.536 MHz, 1.544 MHz for the TP3064, and need not be synchronous. For best transmis-

sion performance, however, $MCLK_R$ should be synchronous with $MCLK_X$, which is easily achieved by applying only static logic levels to the $MCLK_R$ /PDN pin. This will automatically connect $MCLK_X$ to all internal $MCLK_R$ functions (see Pin Description). For 1.544 MHz operation, the device automatically compensates for the 193rd clock pulse each frame. FS_X starts each encoding cycle and must be synchronous with $MCLK_X$ and $BCLK_X$. FS_R starts each decoding cycle and must be synchronous with $BCLK_R$. $BCLK_R$ must be a clock, the logic levels shown in Table I are not valid in asynchronous mode. $BCLK_X$ and $BCLK_R$ may operate from 64 kHz to 2.048 MHz.

SHORT FRAME SYNC OPERATION

The COMBO can utilize either a short frame sync pulse (the same as the TP3020/21 CODECs) or a long frame sync pulse. Upon power initialization, the device assumes a short frame mode. In this mode, both frame sync pulses, FS_X and FS_R , must be one bit clock period long, with timing relationships specified in Figure 2. With FS_X high during a falling edge of $BCLK_X$, the next rising edge of $BCLK_X$ enables the D_X TRI-STATE output buffer, which will output the sign bit. The following seven rising edges clock out the remaining seven bits, and the next falling edge disables the D_X output. With FS_R high during a falling edge of $BCLK_R$ ($BCLK_X$ in synchronous mode), the next falling edge of $BCLK_R$ latches in the sign bit. The following seven falling edges latch in the seven remaining bits. All devices may utilize the short frame sync pulse in synchronous or asynchronous operating mode.

LONG FRAME SYNC OPERATION

To use the long (TP5116A/56 CODECs) frame mode, both the frame sync pulses, FS_X and FS_R , must be three or more bit clock periods long, with timing relationships specified in Figure 3. Based on the transmit frame sync, FS_X , the COMBO will sense whether short or long frame sync pulses are being used. For 64 kHz operation, the frame sync pulse must be kept low for a minimum of 160 ns. The D_X TRI-STATE output buffer is enabled with the rising edge of FS_X or the rising edge of $BCLK_X$, whichever comes later, and the first bit clocked out is the sign bit. The following seven $BCLK_X$ rising edges clock out the remaining seven bits. The D_X output is disabled by the falling $BCLK_X$ edge following the eighth rising edge, or by FS_X going low, whichever comes later. A rising edge on the receive frame sync pulse, FS_R , will cause the PCM data at D_R to be latched in on the next eight falling edges of $BCLK_R$ ($BCLK_X$ in synchronous mode). All devices may utilize the long frame sync pulse in synchronous or asynchronous mode.

TRANSMIT SECTION

The transmit section input is an operational amplifier with provision for gain adjustment using two external resistors, see Figure 4. The low noise and wide bandwidth allow gains in excess of 20 dB across the audio passband to be realized. The op amp drives a unity-gain filter consisting of RC active pre-filter, followed by an eighth order switched-capacitor bandpass filter clocked at 256 kHz. The output of this filter directly drives the encoder sample-and-hold circuit. The A/D is of companding type according to μ -law (TP3064) or A-law (TP3067) coding conventions. A precision voltage reference is trimmed in manufacturing to provide an input overload (t_{MAX}) of nominally 2.5V peak (see

Functional Description (Continued)

table of Transmission Characteristics). The FS_X frame sync pulse controls the sampling of the filter output, and then the successive-approximation encoding cycle begins. The 8-bit code is then loaded into a buffer and shifted out through D_X at the next FS_X pulse. The total encoding delay will be approximately 165 μs (due to the transmit filter) plus 125 μs (due to encoding delay), which totals 290 μs . Any offset voltage due to the filters or comparator is cancelled by sign bit integration.

RECEIVE SECTION

The receive section consists of an expanding DAC which drives a fifth order switched-capacitor low pass filter clocked at 256 kHz. The decoder is A-law (TP3067) or μ -law (TP3064) and the 5th order low pass filter corrects for the $\sin x/x$ attenuation due to the 8 kHz sample/hold. The filter is then followed by a 2nd order RC active post-filter with its output at $VF_R O$. The receive section is unity-gain, but gain can be added by using the power amplifiers. Upon the occurrence of FS_R , the data at the D_R input is clocked in on the falling edge of the next eight $BCLK_R$ ($BCLK_X$) peri-

ods. At the end of the decoder time slot, the decoding cycle begins, and 10 μs later the decoder DAC output is updated. The total decoder delay is $\sim 10 \mu s$ (decoder update) plus 110 μs (filter delay) plus 62.5 μs ($1/2$ frame), which gives approximately 180 μs .

RECEIVE POWER AMPLIFIERS

Two inverting mode power amplifiers are provided for directly driving a matched line interface transformer. The gain of the first power amplifier can be adjusted to boost the $\pm 2.5V$ peak output signal from the receive filter up to $\pm 3.3V$ peak into an unbalanced 300 Ω load, or $\pm 4.0V$ into an unbalanced 15 k Ω load. The second power amplifier is internally connected in unity-gain inverting mode to give 6 dB of signal gain for balanced loads.

Maximum power transfer to a 600 Ω subscriber line termination is obtained by differentially driving a balanced transformer with a $\sqrt{2}$:1 turns ratio, as shown in *Figure 4*. A total peak power of 15.6 dBm can be delivered to the load plus termination.

ENCODING FORMAT AT D_X OUTPUT

	TP3064 μ -Law								TP3067 A-Law (Includes Even Bit Inversion)							
$V_{IN} = +\text{Full-Scale}$	1	0	0	0	0	0	0	0	1	0	1	0	1	0	1	0
$V_{IN} = 0V$	1	1	1	1	1	1	1	1	1	1	0	1	0	1	0	1
	0	1	1	1	1	1	1	1	0	1	0	1	0	1	0	1
$V_{IN} = -\text{Full-Scale}$	0	0	0	0	0	0	0	0	0	0	1	0	1	0	1	0

Absolute Maximum Ratings

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

V_{CC} to GNDA	7V
V_{BB} to GNDA	−7V
Voltage at any Analog Input or Output	$V_{CC} + 0.3V$ to $V_{BB} - 0.3V$

Voltage at any Digital Input or Output	$V_{CC} + 0.3V$ to $GNDA - 0.3V$
Operating Temperature Range	−25°C to +125°C
Storage Temperature Range	−65°C to +150°C
Lead Temp. (Soldering, 10 sec.)	300°C
ESD (Human Body Model) J	1000V
ESD (Human Body Model) N	1500V
Latch-Up Immunity	100 mA on Any Pin

Electrical Characteristics Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for $V_{CC} = +5.0V \pm 5\%$, $V_{BB} = -5.0V \pm 5\%$; $T_A = 0^\circ C$ to $70^\circ C$ by correlation with 100% electrical testing at $T_A = 25^\circ C$. All other limits are assured by correlation with other production tests and/or product design and characterization. All signals referenced to GNDA. Typicals specified at $V_{CC} = +5.0V$, $V_{BB} = -5.0V$, $T_A = 25^\circ C$.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
POWER DISSIPATION (ALL DEVICES)						
I_{CC0}	Power-Down Current	(Note)		0.5	1.5	mA
I_{BB0}	Power-Down Current	(Note)		0.05	0.3	mA
I_{CC1}	Active Current	$V_{PI} = 0V$; V_{FRO} , V_{PO}^+ and V_{PO}^- unloaded		7.0	10.0	mA
I_{BB1}	Active Current	$V_{PI} = 0V$; V_{FRO} , V_{PO}^+ and V_{PO}^- unloaded		7.0	10.0	mA
DIGITAL INTERFACE						
V_{IL}	Input Low Voltage				0.6	V
V_{IH}	Input High Voltage		2.2			V
V_{OL}	Output Low Voltage	D_X , $I_L = 3.2$ mA $\overline{TS}_X$, $I_L = 3.2$ mA, Open Drain			0.4 0.4	V V
V_{OH}	Output High Voltage	D_X , $I_H = -3.2$ mA	2.4			V
I_{IL}	Input Low Current	$GNDA \leq V_{IN} \leq V_{IL}$, All Digital Inputs	− 10		10	μA
I_{IH}	Input High Current	$V_{IH} \leq V_{IN} \leq V_{CC}$	− 10		10	μA
I_{OZ}	Output Current in High Impedance State (TRI-STATE)	D_X , $GNDA \leq V_O \leq V_{CC}$	− 10		10	μA

Note: I_{CC0} and I_{BB0} are measured after first achieving a power-up state.

Electrical Characteristics (Continued)

Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for $V_{CC} = +5.0V \pm 5\%$, $V_{BB} = -5.0V \pm 5\%$; $T_A = 0^\circ\text{C}$ to 70°C by correlation with 100% electrical testing at $T_A = 25^\circ\text{C}$. All other limits are assured by correlation with other production tests and/or product design and characterization. All signals referenced to GNDA. Typicals specified at $V_{CC} = +5.0V$, $V_{BB} = -5.0V$, $T_A = 25^\circ\text{C}$.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
ANALOG INTERFACE WITH TRANSMIT INPUT AMPLIFIER (ALL DEVICES)						
I_{IXA}	Input Leakage Current	$-2.5V \leq V \leq +2.5V$, $V_{FX} ^+$ or $V_{FX} ^-$	-200		200	nA
R_{IXA}	Input Resistance	$-2.5V \leq V \leq +2.5V$, $V_{FX} ^+$ or $V_{FX} ^-$	10			M Ω
R_{OXA}	Output Resistance	Closed Loop, Unity Gain		1	3	Ω
R_{LXA}	Load Resistance	GS_X	10			k Ω
C_{LXA}	Load Capacitance	GS_X			50	pF
V_{OXA}	Output Dynamic Range	GS_X , $R_L \geq 10\text{ k}\Omega$	-2.8		+2.8	V
A_{VXA}	Voltage Gain	$V_{FX} ^+$ to GS_X	5000			V/V
F_{UXA}	Unity-Gain Bandwidth		1	2		MHz
V_{OSXA}	Offset Voltage		-20		20	mV
V_{CMXA}	Common-Mode Voltage	$CMRR_{XA} > 60\text{ dB}$	-2.5		2.5	V
$CMRR_{XA}$	Common-Mode Rejection Ratio	DC Test	60			dB
$PSRR_{XA}$	Power Supply Rejection Ratio	DC Test	60			dB
ANALOG INTERFACE WITH RECEIVE FILTER (ALL DEVICES)						
R_{ORF}	Output Resistance	Pin $V_{FR}O$		1	3	Ω
R_{LRF}	Load Resistance	$V_{FR}O = \pm 2.5V$	10			k Ω
C_{LRF}	Load Capacitance	Connect from $V_{FR}O$ to GNDA			25	pF
V_{OSRO}	Output DC Offset Voltage	Measure from $V_{FR}O$ to GNDA	-200		200	mV
ANALOG INTERFACE WITH POWER AMPLIFIERS (ALL DEVICES)						
I_{PI}	Input Leakage Current	$-1.0V \leq V_{PI} \leq 1.0V$	-100		100	nA
R_{PI}	Input Resistance	$-1.0V \leq V_{PI} \leq 1.0V$	10			M Ω
V_{IOS}	Input Offset Voltage		-25		25	mV
R_{OP}	Output Resistance	Inverting Unity-Gain at V_{PO}^+ or V_{PO}^-		1		Ω
F_C	Unity-Gain Bandwidth	Open Loop (V_{PO}^-)		400		kHz
C_{LP}	Load Capacitance				100	pF
GA_{P^+}	Gain from V_{PO}^- to V_{PO}^+	$R_L = 600\Omega$ V_{PO}^+ to V_{PO}^- Level at $V_{PO}^- = 1.77\text{ V}_{rms}$		-1		V/V
$PSRR_P$	Power Supply Rejection of V_{CC} or V_{BB}	V_{PO}^- Connected to VPI 0 kHz – 4 kHz 4 kHz – 50 kHz	60 36			dB dB
R_{LP}	Load Resistance	Connect from V_{PO}^+ to V_{PO}^-	600			Ω

Timing Specifications

Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for $V_{CC} = +5.0V \pm 5\%$, $V_{BB} = -5.0V \pm 5\%$, $T_A = 0^\circ C$ to $70^\circ C$ by correlation with 100% electrical testing at $T_A = 25^\circ C$. All other limits are assured by correlation with other production tests and/or product design and characterization. All signals are referenced to GND. Typical values specified at $V_{CC} = +5.0V$, $V_{BB} = -5.0V$, $T_A = 25^\circ C$. All timing parameters are measured at $V_{OH} = 2.0V$ and $V_{OL} = 0.7V$.

See Definitions and Timing Conventions section for test methods information.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$1/t_{PM}$	Frequency of Master Clock	$MCLK_X$ and $MCLK_R$		1.536 1.544 2.048		MHz MHz MHz
t_{RM}	Rise Time of Master Clock	$MCLK_X$ and $MCLK_R$			50	ns
t_{FM}	Fall Time of Master Clock	$MCLK_X$ and $MCLK_R$			50	ns
t_{PB}	Period Bit of Clock		485	488	15725	ns
t_{RB}	Rise Time of Bit Clock	$BCLK_X$ and $BCLK_R$			50	ns
t_{FB}	Fall Time of Bit Clock	$BCLK_X$ and $BCLK_R$			50	ns
t_{WMH}	Width of Master Clock High	$MCLK_X$ and $MCLK_R$	160			ns
t_{WML}	Width of Master Clock Low	$MCLK_X$ and $MCLK_R$	160			ns
t_{SBFM}	Set-Up Time from $BCLK_X$ High to $MCLK_X$ Falling Edge		100			ns
t_{SFFM}	Set-Up Time from FS_X High to $MCLK_X$ Falling Edge	Long Frame Only	100			ns
t_{WBH}	Width of Bit Clock High		160			ns
t_{WBL}	Width of Bit Clock Low		160			ns
t_{HBFL}	Holding Time from Bit Clock Low to Frame Sync	Long Frame Only	0			ns
t_{HBFS}	Holding Time from Bit Clock High to Frame Sync	Short Frame Only	0			ns
t_{SFB}	Set-Up Time for Frame Sync to Bit Clock Low	Long Frame Only	80			ns
t_{DBD}	Delay Time from $BCLK_X$ High to Data Valid	Load = 150 pF plus 2 LSTTL Loads	0		180	ns
t_{DBTS}	Delay Time to $\overline{TS_X}$ Low	Load = 150 pF plus 2 LSTTL Loads			140	ns
t_{DZC}	Delay Time from $BCLK_X$ Low to Data Output Disabled		50		165	ns
t_{DZF}	Delay Time to Valid Data from FS_X or $BCLK_X$, Whichever Comes Later	$C_L = 0$ pF to 150 pF	20		165	ns
t_{SDB}	Set-Up Time from D_R Valid to $BCLK_{R/X}$ Low		50			ns
t_{HBD}	Hold Time from $BCLK_{R/X}$ Low to D_R Invalid		50			ns
t_{SF}	Set-Up Time from $FS_{X/R}$ to $BCLK_{X/R}$ Low	Short Frame Sync Pulse (1 Bit Clock Period Long)	50			ns
t_{HF}	Hold Time from $BCLK_{X/R}$ Low to $FS_{X/R}$ Low	Short Frame Sync Pulse (1 Bit Clock Period Long)	100			ns
t_{HBF}	Hold Time from 3rd Period of Bit Clock Low to Frame Sync (FS_X or FS_R)	Long Frame Sync Pulse (from 3 to 8 Bit Clock Periods Long)	100			ns
t_{WFL}	Minimum Width of the Frame Sync Pulse (Low Level)	64k Bit/s Operating Mode	160			ns

Timing Diagrams

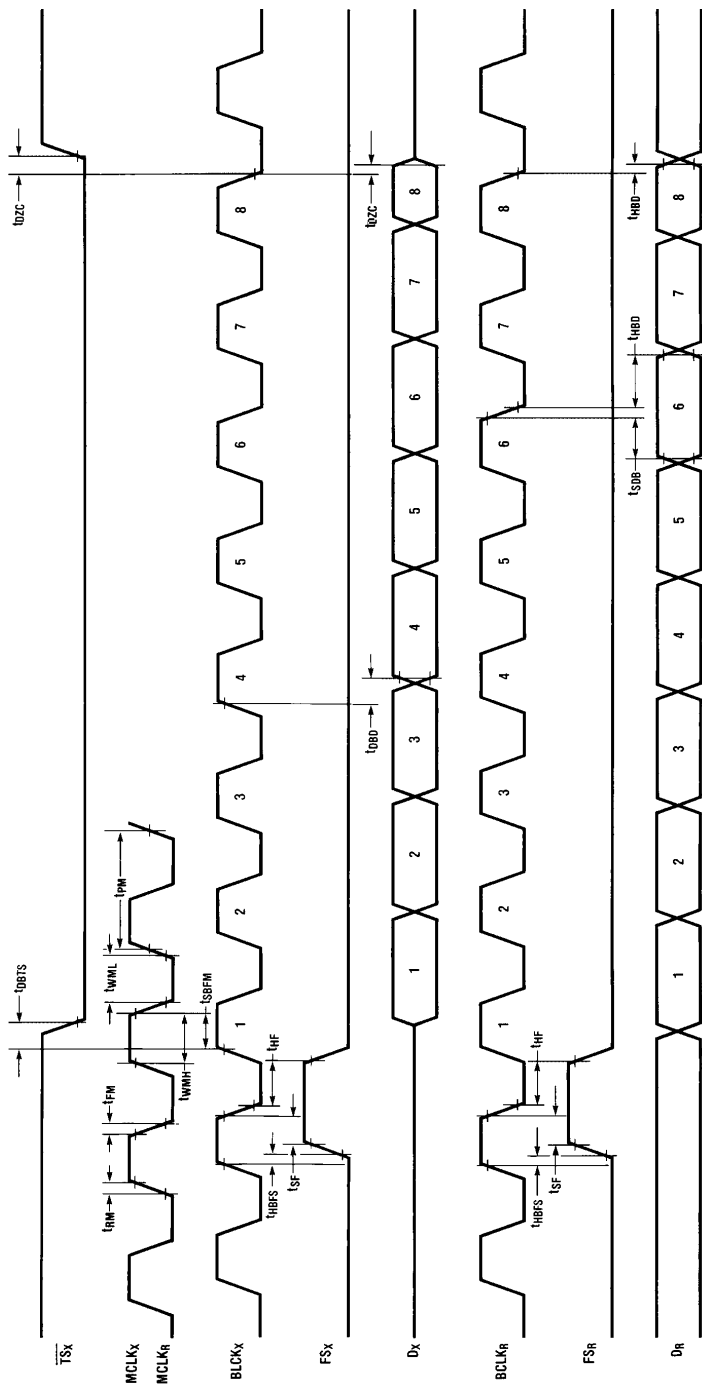
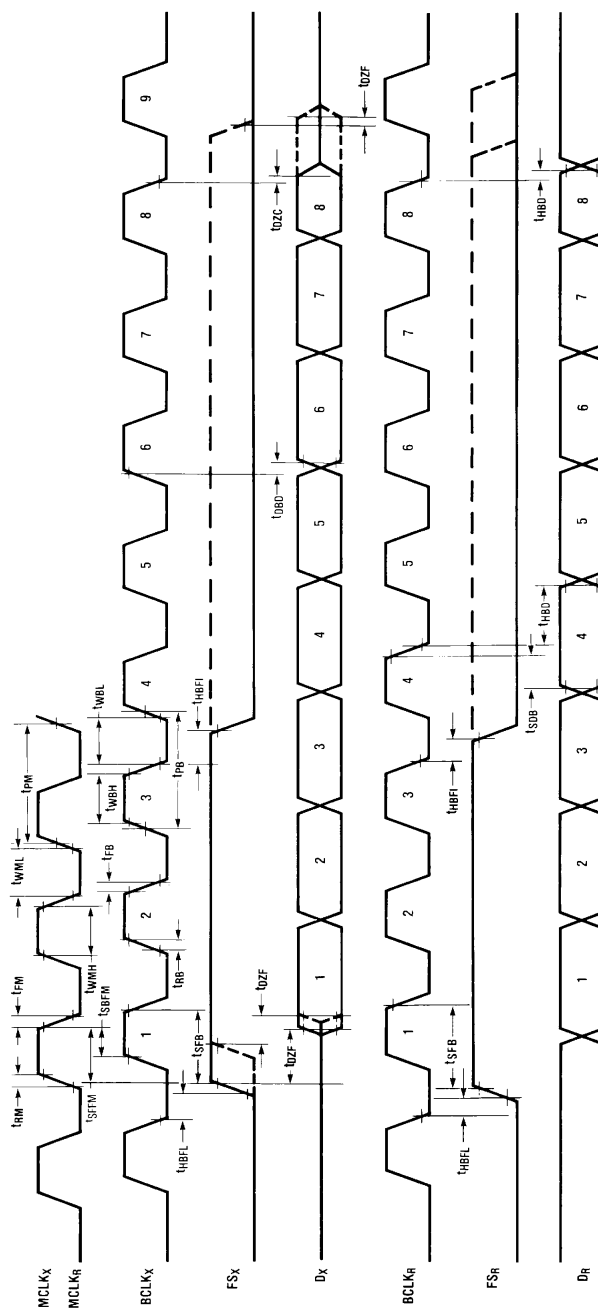


FIGURE 2. Short Frame Sync Timing

TL/H/5070-3

Timing Diagrams (Continued)



TL/H/5070-4

Transmission Characteristics

Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for $V_{CC} = +5.0V \pm 5\%$, $V_{BB} = -5.0V \pm 5\%$; $T_A = 0^\circ\text{C}$ to 70°C by correlation with 100% electrical testing at $T_A = 25^\circ\text{C}$. All other limits are assured by correlation with other production tests and/or product design and characterization. $G_{NDA} = 0V$, $f = 1.02\text{ kHz}$, $V_{IN} = 0\text{ dBm0}$, transmit input amplifier connected for unity gain non-inverting. Typicals specified at $V_{CC} = +5.0V$, $V_{BB} = -5.0V$, $T_A = 25^\circ\text{C}$.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
AMPLITUDE RESPONSE						
	Absolute Levels (Definition of nominal gain)	Nominal 0 dBm0 Level is 4 dBm (600 Ω) 0 dBm0		1.2276		V _{rms}
t _{MAX}	Virtual Decision Value Defined per CCITT Rec. G711	Max Transmit Overload Level TP3064 (3.17 dBm0) TP3067 (3.14 dBm0)		2.501 2.492		V _{PK} V _{PK}
G _{XA}	Transmit Gain, Absolute	T _A = 25°C, V _{CC} = 5V, V _{BB} = -5V	-0.15		0.15	dB
G _{XR}	Transmit Gain, Relative to G _{XA}	f = 16 Hz f = 50 Hz f = 60 Hz f = 200 Hz f = 300 Hz-3000 Hz f = 3300 Hz f = 3400 Hz f = 4000 Hz f = 4600 Hz and Up, Measure Response from 0 Hz to 4000 Hz	-1.8 -0.15 -0.35 -0.7		-40 -30 -26 -0.1 0.15 0.05 0 -14 -32	dB dB dB dB dB dB dB dB dB
G _{XAT}	Absolute Transmit Gain Variation with Temperature	Relative to G _{XA}	-0.1		0.1	dB
G _{XAV}	Absolute Transmit Gain Variation with Supply Voltage	Relative to G _{XA}	-0.05		0.05	dB
G _{XRL}	Transmit Gain Variations with Level	Sinusoidal Test Method Reference Level = -10 dBm0 V _{F_XL} ⁺ = -40 dBm0 to +3 dBm0 V _{F_XL} ⁺ = -50 dBm0 to -40 dBm0 V _{F_XL} ⁺ = -55 dBm0 to -50 dBm0	-0.2 -0.4 -1.2		0.2 0.4 1.2	dB dB dB
G _{RA}	Receive Gain, Absolute	T _A = 25°C, V _{CC} = 5V, V _{BB} = -5V Input = Digital Code Sequence for 0 dBm0 Signal	-0.15		0.15	dB
G _{RR}	Receive Gain, Relative to G _{RA}	f = 0 Hz to 3000 Hz f = 3300 Hz f = 3400 Hz f = 4000 Hz	-0.15 -0.35 -0.7		0.15 0.05 0 -14	dB dB dB dB
G _{RAT}	Absolute Receive Gain Variation with Temperature	Relative to G _{RA}	-0.1		0.1	dB
G _{RAV}	Absolute Receive Gain Variation with Supply Voltage	Relative to G _{RA}	-0.05		0.05	dB
G _{RRL}	Receive Gain Variations with Level	Sinusoidal Test Method; Reference Input PCM Code Corresponds to an Ideally Encoded -10 dBm0 Signal PCM Level = -40 dBm0 to +3 dBm0 PCM Level = -50 dBm0 to -40 dBm0 PCM Level = -55 dBm0 to -50 dBm0	-0.2 -0.4 -1.2		0.2 0.4 1.2	dB dB dB
V _{RO}	Receive Filter Output at V _{FRO}	RL = 10 k Ω	-2.5		2.5	V

Transmission Characteristics (Continued)

Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for $V_{CC} = +5.0V \pm 5\%$, $V_{BB} = -5.0V \pm 5\%$; $T_A = 0^\circ C$ to $70^\circ C$ by correlation with 100% electrical testing at $T_A = 25^\circ C$. All other limits are assured by correlation with other production tests and/or product design and characterization. $GNDA = 0V$, $f = 1.02 \text{ kHz}$, $V_{IN} = 0 \text{ dBm0}$, transmit input amplifier connected for unity gain non-inverting. Typicals specified at $V_{CC} = +5.0V$, $V_{BB} = -5.0V$, $T_A = 25^\circ C$.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
ENVELOPE DELAY DISTORTION WITH FREQUENCY						
D _{XA}	Transmit Delay, Absolute	f = 1600 Hz		290	315	μs
D _{XR}	Transmit Delay, Relative to D _{XA}	f = 500 Hz – 600 Hz		195	220	μs
		f = 600 Hz – 800 Hz		120	145	μs
		f = 800 Hz – 1000 Hz		50	75	μs
		f = 1000 Hz – 1600 Hz		20	40	μs
		f = 1600 Hz – 2600 Hz		55	75	μs
		f = 2600 Hz – 2800 Hz		80	105	μs
		f = 2800 Hz – 3000 Hz		130	155	μs
D _{RA}	Receive Delay, Absolute	f = 1600 Hz		180	200	μs
D _{RR}	Receive Delay, Relative to D _{RA}	f = 500 Hz – 1000 Hz	–40	–25		μs
		f = 1000 Hz – 1600 Hz	–30	–20		μs
		f = 1600 Hz – 2600 Hz		70	90	μs
		f = 2600 Hz – 2800 Hz		100	125	μs
		f = 2800 Hz – 3000 Hz		145	175	μs
NOISE						
N _{XC}	Transmit Noise, C Message Weighted	TP3064 (Note 1)		12	15	dBrnC0
N _{XP}	Transmit Noise, Psophometric Weighted	TP3067 (Note 1)		–74	–67	dBm0p
N _{RC}	Receive Noise, C Message Weighted	PCM Code Equals Alternating Positive and Negative Zero TP3064		8	11	dBrnC0
N _{RP}	Receive Noise, Psophometric Weighted	PCM Code Equals Positive Zero TP3067		–82	–79	dBm0p
N _{RS}	Noise, Single Frequency	f = 0 kHz to 100 kHz, Loop Around Measurement, V _{FXI} ⁺ = 0 Vrms			–53	dBm0
PPSR _X	Positive Power Supply Rejection, Transmit	V _{CC} = 5.0 V _{DC} + 100 mVrms f = 0 kHz – 50 kHz (Note 2)	40			dBc
NPSR _X	Negative Power Supply Rejection, Transmit	V _{BB} = –5.0 V _{DC} + 100 mVrms f = 0 kHz – 50 kHz (Note 2)	40			dBc
PPSR _R	Positive Power Supply Rejection, Receive	PCM Code Equals Positive Zero V _{CC} = 5.0 V _{DC} + 100 mVrms Measure V _{FR0} f = 0 Hz – 4000 Hz f = 4 kHz – 50 kHz	38 25			dBc dB
NPSR _R	Negative Power Supply Rejection, Receive	PCM Code Equals Positive Zero V _{BB} = –5.0 V _{DC} + 100 mVrms Measure V _{FR0} f = 0 Hz – 4000 Hz f = 4 kHz – 25 kHz f = 25 kHz – 50 kHz	40 40 36			dBc dB dB
SOS	Spurious Out-of-Band Signals at the Channel Output	0 dBm0, 300 Hz – 3400 Hz Input PCM Code Applied at DR Measure Individual Image Signals at V _{FR0} 4600 Hz – 7600 Hz 7600 Hz – 8400 Hz 8400 Hz – 100,000 Hz			–32 –40 –32	dB dB dB

Transmission Characteristics (Continued)

Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for $V_{CC} = +5.0V \pm 5\%$, $V_{BB} = -5.0V \pm 5\%$; $T_A = 0^\circ C$ to $70^\circ C$ by correlation with 100% electrical testing at $T_A = 25^\circ C$. All other limits are assured by correlation with other production tests and/or product design and characterization. $G_{NDA} = 0V$, $f = 1.02 \text{ kHz}$, $V_{IN} = 0 \text{ dBm0}$, transmit input amplifier connected for unity gain non-inverting. Typicals specified at $V_{CC} = +5.0V$, $V_{BB} = -5.0V$, $T_A = 25^\circ C$.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
DISTORTION						
STD _X , STD _R	Signal to Total Distortion Transmit or Receive Half-Channel	Sinusoidal Test Method (Note 3) Level = 3.0 dBm0 = 0 dBm0 to -30 dBm0 = -40 dBm0 XMT RCV = -55 dBm0 XMT RCV	33 36 29 30 14 15			dBc dBc dBc dBc dBc dBc
SFD _X	Single Frequency Distortion, Transmit				-46	dB
SFD _R	Single Frequency Distortion, Receive				-46	dB
IMD	Intermodulation Distortion	Loop Around Measurement, $VF_{X1}^+ = -4 \text{ dBm0}$ to -21 dBm0 , Two Frequencies in the Range 300 Hz – 3400 Hz			-41	dB
CROSSTALK						
CT _{X-R}	Transmit to Receive Crosstalk	$f = 300 \text{ Hz} - 3000 \text{ Hz}$ $D_R = \text{Quiet PCM Code}$		-90	-75	dB
CT _{R-X}	Receive to Transmit Crosstalk	$f = 300 \text{ Hz} - 3000 \text{ Hz}$, $VF_{X1} = 0V$ (Note 2)		-90	-70	dB
POWER AMPLIFIERS						
V _{OPA}	Maximum 0 dBm0 Level (Better than $\pm 0.1 \text{ dB}$ Linearity over the Range -10 dBm0 to +3 dBm0)	Balanced Load, R_L Connected Between VPO^+ and VPO^- . $R_L = 600\Omega$ $R_L = 1200\Omega$	3.3 3.5			Vrms Vrms
S/D _P	Signal/Distortion	$R_L = 600\Omega$	50			dB

Note 1: Measured by extrapolation from the distortion test result at -50 dBm0.

Note 2: PPSR_X, NPSR_X, and CT_{R-X} are measured with a -50 dBm0 activation signal applied to VF_{X1}^+ .

Note 3: TP3064 is measured using C message weighted filter. TP3067 is measured using psophometric weighted filter.

Applications Information

POWER SUPPLIES

While the pins of the TP3060 family are well protected against electrical misuse, it is recommended that the standard CMOS practice be followed, ensuring that ground is connected to the device before any other connections are made. In applications where the printed circuit board may be plugged into a "hot" socket with power and clocks already present, an extra long ground pin in the connector should be used.

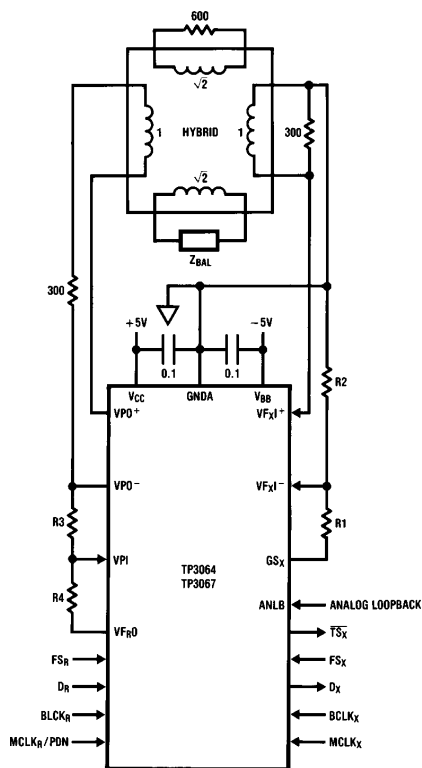
All ground connections to each device should meet at a common point as close as possible to the GNDA pin. This

minimizes the interaction of ground return currents flowing through a common bus impedance. 0.1 μF supply decoupling capacitors should be connected from this common ground point to V_{CC} and V_{BB} , as close to the device as possible.

For best performance, the ground point of each CODEC/FILTER on a card should be connected to a common card ground in "STAR" formation, rather than via a ground bus. This common ground point should be decoupled to V_{CC} and V_{BB} with 10 μF capacitors.

Note: See Application Note 370 for further details

Typical Asynchronous Application



Note 1: Transmit gain = $20 \times \log \left(\frac{R1 + R2}{R2} \right)$, $(R1 + R2) \geq 10 \text{ k}\Omega$

Note 2: Receive gain = $20 \times \log \left(\frac{2 \times R3}{R4} \right)$, $R4 \geq 10 \text{ k}\Omega$

FIGURE 4

Definitions and Timing Conventions

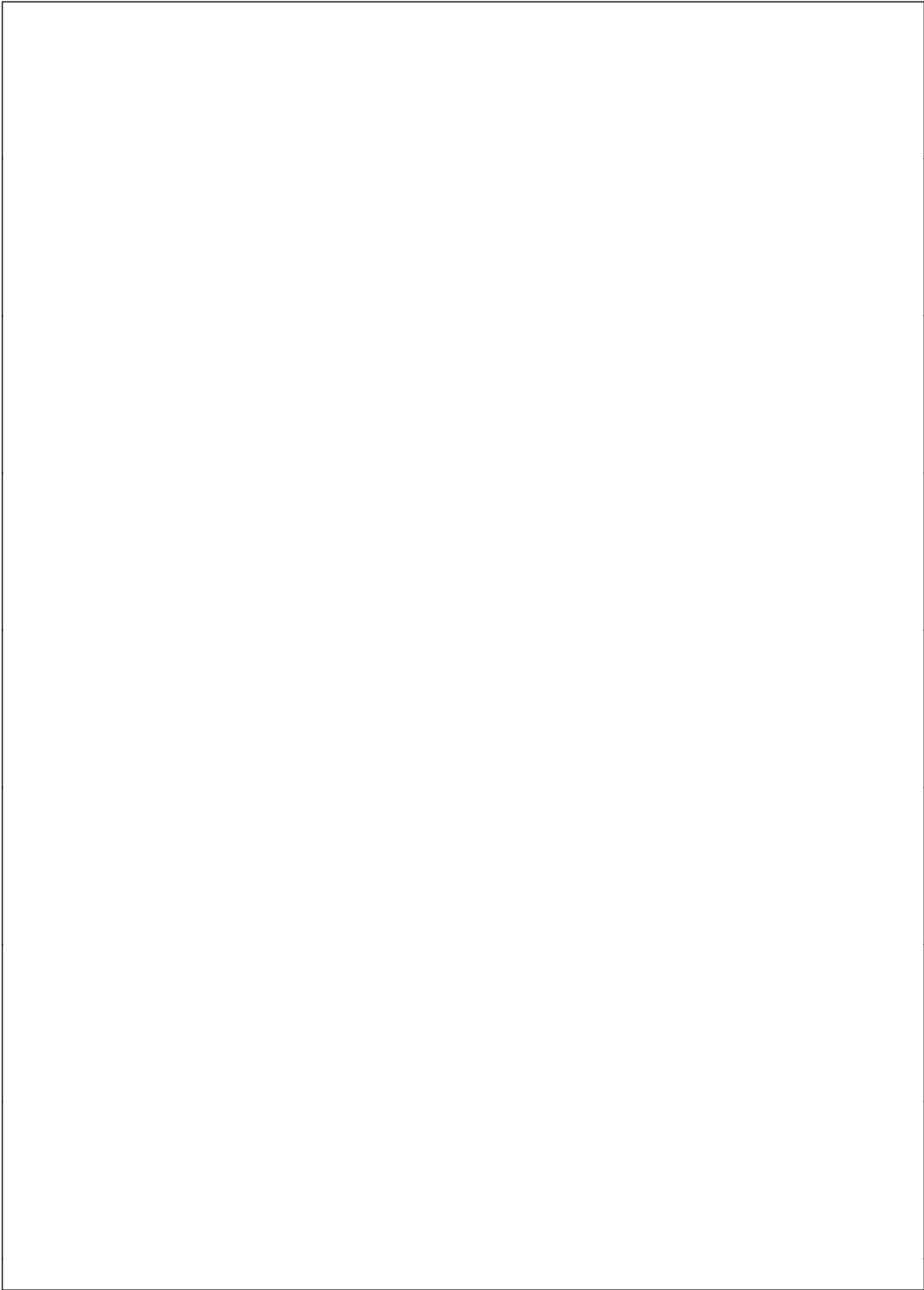
DEFINITIONS

V_{IH}	V_{IH} is the d.c. input level above which an input level is guaranteed to appear as a logical one. This parameter is to be measured by performing a functional test at reduced clock speeds and nominal timing, (i.e. not minimum setup and hold times or output strobes), with the high level of all driving signals set to V_{IH} and maximum supply voltages applied to the device
V_{IL}	V_{IL} is the d.c. input level below which an input level is guaranteed to appear as a logical zero to the device. This parameter is measured in the same manner as V_{IH} but with all driving signal low levels set to V_{IL} and minimum supply voltages applied to the device.
V_{OH}	V_{OH} is the minimum d.c. output level to which an output placed in a logical one state will converge when loaded at the maximum specified load current.
V_{OL}	V_{OL} is the maximum d.c. output level to which an output placed in a logical zero state will converge when loaded at the maximum specified load current.
Threshold Region	The threshold region is the range of input voltages between V_{IL} and V_{IH} .
Valid Signal	A signal is Valid if it is in one of the valid logic states, (i.e. above V_{IH} or below V_{IL}). In timing specifications, a signal is deemed valid at the instant it enters a valid state.
Invalid Signal	A signal is Invalid if it is not in a valid logic state, i.e. when it is in the threshold region between V_{IL} and V_{IH} . In timing specifications, a signal is deemed Invalid at the instant it enters the threshold region.

TIMING CONVENTIONS

For the purposes of this timing specification, the following conventions apply:

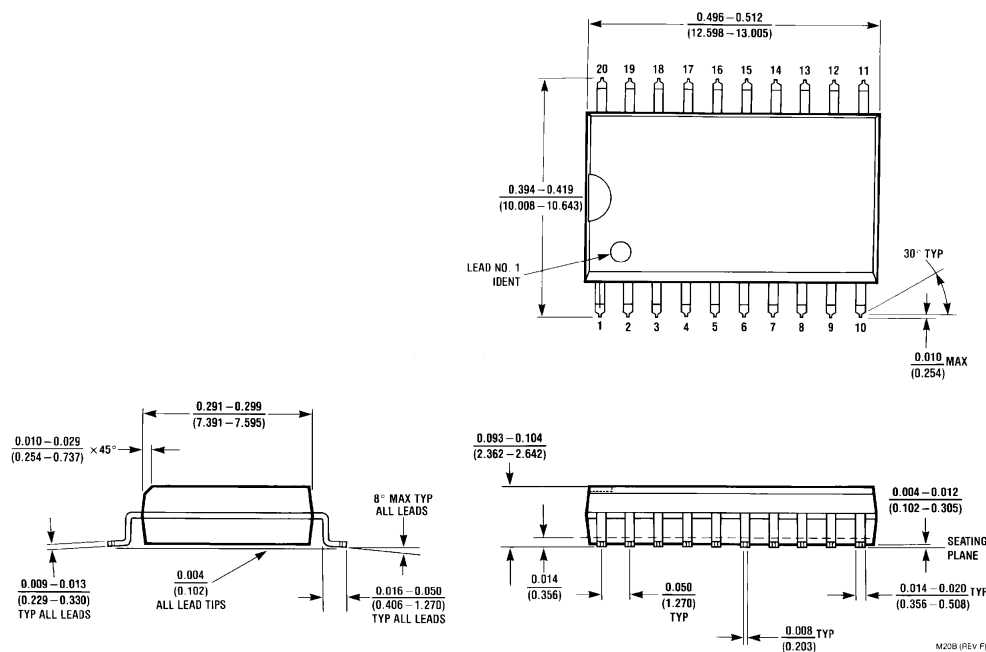
Input Signals	All input signals may be characterized as: $V_L = 0.4V$, $V_H = 2.4V$, $t_R < 10$ ns, $t_F < 10$ ns.
Period	The period of clock signal is designated as t_{Pxx} where xx represents the mnemonic of the clock signal being specified.
Rise Time	Rise times are designated as t_{Ryy} , where yy represents a mnemonic of the signal whose rise time is being specified. t_{Ryy} is measured from V_{IL} to V_{IH} .
Fall Time	Fall times are designated as t_{Fyy} , where yy represents a mnemonic of the signal whose fall time is being specified. t_{Fyy} is measured from V_{IH} to V_{IL} .
Pulse Width High	The high pulse width is designated as t_{WzzH} , where zz represents the mnemonic of the input or output signal whose pulse width is being specified. High pulse widths are measured from V_{IH} to V_{IH} .
Pulse Width Low	The low pulse width is designated as t_{WzzL} , where zz represents the mnemonic of the input or output signal whose pulse width is being specified. Low pulse widths are measured from V_{IL} to V_{IL} .
Setup Time	Setup times are designated as t_{Swwxx} , where ww represents the mnemonic of the input signal whose setup time is being specified relative to a clock or strobe input represented by mnemonic xx. Setup times are measured from the ww Valid to xx Invalid.
Hold Time	Hold times are designated as t_{Hxxww} , where ww represents the mnemonic of the input signal whose hold time is being specified relative to a clock or strobe input represented by mnemonic xx. Hold times are measured from xx Valid to ww Invalid.
Delay Time	Delay times are designated as t_{Dxxyy} Hi to Low, where xx represents the mnemonic of the input reference signal and yy represents the mnemonic of the output signal whose timing is being specified relative to xx. The mnemonic may optionally be terminated by an H or L to specify the high going or low going transition of the output signal. Maximum delay times are measured from xx Valid to yy Valid. Minimum delay times are measured from xx Valid to yy Invalid. This parameter is tested under the load conditions specified in the Conditions column of the Timing Specifications section of this data sheet.



Top View Dimensions:

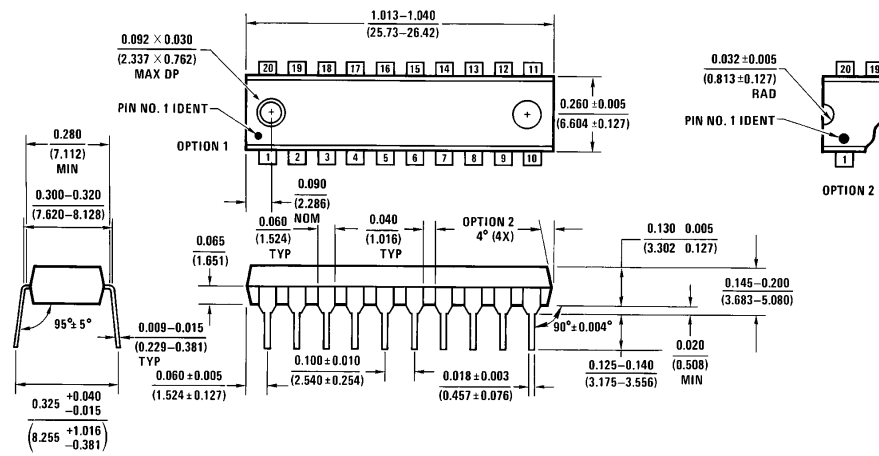
- Overall width: 0.985 (25.019) MAX
- Pin pitch (between pins 1 and 10): 0.085 (2.159) MAX
- Pin 1 to Pin 10 distance: 0.895 (22.822) MAX
- Pin 1 to Pin 11 distance: 0.985 (25.019) MAX
- Pin 1 to Pin 12 distance: 1.070 (27.184) MAX
- Pin 1 to Pin 13 distance: 1.155 (29.339) MAX
- Pin 1 to Pin 14 distance: 1.240 (31.494) MAX
- Pin 1 to Pin 15 distance: 1.325 (33.649) MAX
- Pin 1 to Pin 16 distance: 1.410 (35.804) MAX
- Pin 1 to Pin 17 distance: 1.495 (37.959) MAX
- Pin 1 to Pin 18 distance: 1.580 (40.114) MAX
- Pin 1 to Pin 19 distance: 1.665 (42.269) MAX
- Pin 1 to Pin 20 distance: 1.750 (44.424) MAX
- Pin 1 to Pin 21 distance: 1.835 (46.579) MAX
- Pin 1 to Pin 22 distance: 1.920 (48.734) MAX
- Pin 1 to Pin 23 distance: 2.005 (50.889) MAX
- Pin 1 to Pin 24 distance: 2.090 (53.044) MAX
- Pin 1 to Pin 25 distance: 2.175 (55.199) MAX
- Pin 1 to Pin 26 distance: 2.260 (57.354) MAX
- Pin 1 to Pin 27 distance: 2.345 (59.509) MAX
- Pin 1 to Pin 28 distance: 2.430 (61.664) MAX
- Pin 1 to Pin 29 distance: 2.515 (63.819) MAX
- Pin 1 to Pin 30 distance: 2.600 (65.974) MAX
- Pin 1 to Pin 31 distance: 2.685 (68.129) MAX
- Pin 1 to Pin 32 distance: 2.770 (70.284) MAX
- Pin 1 to Pin 33 distance: 2.855 (72.439) MAX
- Pin 1 to Pin 34 distance: 2.940 (74.594) MAX
- Pin 1 to Pin 35 distance: 3.025 (76.749) MAX
- Pin 1 to Pin 36 distance: 3.110 (78.904) MAX
- Pin 1 to Pin 37 distance: 3.195 (81.059) MAX
- Pin 1 to Pin 38 distance: 3.280 (83.214) MAX
- Pin 1 to Pin 39 distance: 3.365 (85.369) MAX
- Pin 1 to Pin 40 distance: 3.450 (87.524) MAX
- Pin 1 to Pin 41 distance: 3.535 (89.679) MAX
- Pin 1 to Pin 42 distance: 3.620 (91.834) MAX
- Pin 1 to Pin 43 distance: 3.705 (93.989) MAX
- Pin 1 to Pin 44 distance: 3.790 (96.144) MAX
- Pin 1 to Pin 45 distance: 3.875 (98.299) MAX
- Pin 1 to Pin 46 distance: 3.960 (100.454) MAX
- Pin 1 to Pin 47 distance: 4.045 (102.609) MAX
- Pin 1 to Pin 48 distance: 4.130 (104.764) MAX
- Pin 1 to Pin 49 distance: 4.215 (106.919) MAX
- Pin 1 to Pin 50 distance: 4.300 (109.074) MAX
- Pin 1 to Pin 51 distance: 4.385 (111.229) MAX
- Pin 1 to Pin 52 distance: 4.470 (113.384) MAX
- Pin 1 to Pin 53 distance: 4.555 (115.539) MAX
- Pin 1 to Pin 54 distance: 4.640 (117.694) MAX
- Pin 1 to Pin 55 distance: 4.725 (119.849) MAX
- Pin 1 to Pin 56 distance: 4.810 (122.004) MAX
- Pin 1 to Pin 57 distance: 4.895 (124.159) MAX
- Pin 1 to Pin 58 distance: 4.980 (126.314) MAX
- Pin 1 to Pin 59 distance: 5.065 (128.469) MAX
- Pin 1 to Pin 60 distance: 5.150 (130.624) MAX
- Pin 1 to Pin 61 distance: 5.235 (132.779) MAX
- Pin 1 to Pin 62 distance: 5.320 (134.934) MAX
- Pin 1 to Pin 63 distance: 5.405 (137.089) MAX
- Pin 1 to Pin 64 distance: 5.490 (139.244) MAX
- Pin 1 to Pin 65 distance: 5.575 (141.399) MAX
- Pin 1 to Pin 66 distance: 5.660 (143.554) MAX
- Pin 1 to Pin 67 distance: 5.745 (145.709) MAX
- Pin 1 to Pin 68 distance: 5.830 (147.864) MAX
- Pin 1 to Pin 69 distance: 5.915 (149.919) MAX
- Pin 1 to Pin 70 distance: 6.000 (152.074) MAX
- Pin 1 to Pin 71 distance: 6.085 (154.229) MAX
- Pin 1 to Pin 72 distance: 6.170 (156.384) MAX
- Pin 1 to Pin 73 distance: 6.255 (158.539) MAX
- Pin 1 to Pin 74 distance: 6.340 (160.694) MAX
- Pin 1 to Pin 75 distance: 6.425 (162.849) MAX
- Pin 1 to Pin 76 distance: 6.510 (165.004) MAX
- Pin 1 to Pin 77 distance: 6.595 (167.159) MAX
- Pin 1 to Pin 78 distance: 6.680 (169.314) MAX
- Pin 1 to Pin 79 distance: 6.765 (171.469) MAX
- Pin 1 to Pin 80 distance: 6.850 (173.624) MAX
- Pin 1 to Pin 81 distance: 6.935 (175.779) MAX
- Pin 1 to Pin 82 distance: 7.020 (177.934) MAX
- Pin 1 to Pin 83 distance: 7.105 (180.089) MAX
- Pin 1 to Pin 84 distance: 7.190 (182.244) MAX
- Pin 1 to Pin 85 distance: 7.275 (184.399) MAX
- Pin 1 to Pin 86 distance: 7.360 (186.554) MAX
- Pin 1 to Pin 87 distance: 7.445 (188.709) MAX
- Pin 1 to Pin 88 distance: 7.530 (190.864) MAX
- Pin 1 to Pin 89 distance: 7.615 (193.019) MAX
- Pin 1 to Pin 90 distance: 7.700 (195.174) MAX
- Pin 1 to Pin 91 distance: 7.785 (197.329) MAX
- Pin 1 to Pin 92 distance: 7.870 (199.484) MAX
- Pin 1 to Pin 93 distance: 7.955 (201.639) MAX
- Pin 1 to Pin 94 distance: 8.040 (203.794) MAX
- Pin 1 to Pin 95 distance: 8.125 (205.949) MAX
- Pin 1 to Pin 96 distance: 8.210 (208.104) MAX
- Pin 1 to Pin 97 distance: 8.295 (210.259) MAX
- Pin 1 to Pin 98 distance: 8.380 (212.414) MAX
- Pin 1 to Pin 99 distance: 8.465 (214.569) MAX
- Pin 1 to Pin 100 distance: 8.550 (216.724) MAX
- Pin 1 to Pin 101 distance: 8.635 (218.879) MAX
- Pin 1 to Pin 102 distance: 8.720 (221.034) MAX
- Pin 1 to Pin 103 distance: 8.805 (223.189) MAX
- Pin 1 to Pin 104 distance: 8.890 (225.344) MAX
- Pin 1 to Pin 105 distance: 8.975 (227.499) MAX
- Pin 1 to Pin 106 distance: 9.060 (229.654) MAX
- Pin 1 to Pin 107 distance: 9.145 (231.809) MAX
- Pin 1 to Pin 108 distance: 9.230 (233.964) MAX
- Pin 1 to Pin 109 distance: 9.315 (236.119) MAX
- Pin 1 to Pin 110 distance: 9.400 (238.274) MAX
- Pin 1 to Pin 111 distance: 9.485 (240.429) MAX
- Pin 1 to Pin 112 distance: 9.570 (242.584) MAX
- Pin 1 to Pin 113 distance: 9.655 (244.739) MAX
- Pin 1 to Pin 114 distance: 9.740 (246.894) MAX
- Pin 1 to Pin 115 distance: 9.825 (249.049) MAX
- Pin 1 to Pin 116 distance: 9.910 (251.204) MAX
- Pin 1 to Pin 117 distance: 9.995 (253.359) MAX
- Pin

Cavity Dual-In-Line Package (J)
Order Number TP3064J or TP3067J
NS Package Number J20A



Molded Small Outline Package (WM)
Order Number TP3064WM or TP3067WM
NS Package Number M20B

Physical Dimensions inches (millimeters) (Continued)

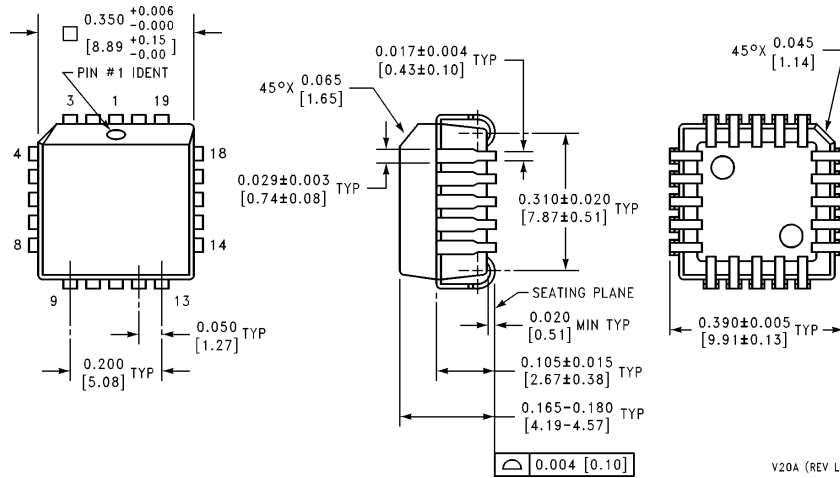


N20A (REV G)

Molded Dual-In-Line Package (N)
Order Number TP3064N or TP3067N
NS Package Number N20A

Physical Dimensions inches (millimeters) (Continued)

Lit. # 113975



Plastic Chip Carrier (V)
Order Number TP3064V or TP3067V
NS Package Number V20A

V20A (REV L)

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